

L-529

Solution Coated Epoxy Prepreg



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Product Data Sheet

Description

L-529 is a solution coated epoxy prepreg with superior cosmetic and mechanical properties. It is a versatile 'general purpose' product. L-529 is available on fiberglass fabrics such as 7781 or other styles as requested.

Advantages of L-529

- ❖ L-529 is used in a wide variety of commercial applications (for example, sporting goods, high-performance automobile parts, high-performance boating parts).
- ❖ It is often specified by designers for laminating (as opposed to sandwich) construction.

Physical Properties on 7781 Glass Fabric

- *Standard Resin Content: 38% by weight*
- *Volatile Content: Less than 5% by weight*
- *Standard Tack: Medium*
- *Cured Ply Thickness: 0.010" (0.254 mm)*
- *Standard Weights: 0.100 lbs/ft² (488 g/m²)*
- *Optional Weights: 0.045 lbs/ft² (220 g/m²)*
0.075 lbs/ft² (366 g/m²)
0.090 lbs/ft² (439 g/m²)
Other weights are available.
- *Various supporting carriers, both woven and non-woven, are available.*

Availability

- *Up to 60" width in rolls up to 100 yards long (152 cm x 91 m)*

Shelf Life

- *4 months at 40°F (4°C) or below*
- *7 days at Room Temperature (70°F or 21°C)*

Cure Cycle

- *60 minutes at 250-275°F (121-135°C). Adjust pressure as necessary*

Mechanical Data

PROPERTY	LAMINATE PROPERTIES		
	7781	U.D. S-2 / 0°	TEST METHOD
ULTIMATE TENSILE STRENGTH Room Temperature (RT) 160°F (71°C)	62 KSI (428 MPa) 48 KSI (331 MPa)	172 KSI (1.2 GPa) 165 KSI (1.1 GPa)	ASTM D638 ASTM D638
TENSILE MODULUS Room Temperature (RT) 160°F (71°C)	3.2 MSI (22 GPa) 3.1 MSI (21 GPa)	7.5 MSI (52 GPa) 7.5 MSI (52 GPa)	ASTM D638 ASTM D638
COMPRESSIVE STRENGTH Room Temperature (RT)	62 KSI (428 MPa)	97 KSI (669 MPa)	ASTM D695
COMPRESSIVE MODULUS Room Temperature (RT)	3.7 MSI (26 GPa)	8.3 MSI (57 GPa)	ASTM D695
ULTIMATE FLEXURAL STRENGTH Room Temperature (RT)	85 KSI (586 MPa)	175 KSI (1.2 GPa)	ASTM D790
FLEXURAL MODULUS Room Temperature (RT)	4.0 KSI (28 MPa)	7.8 KSI (54 MPa)	ASTM D790

NOTICE:

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